11	IENT TRANSMIT	tity)		Docket No.				
Applicant(s): Hyu		SEC.836						
		g Date gust 2001 Sc		Examiner ott B. GEYER		Group Art Unit 2829		
Inventon: E EQUIP	PMENT FOR FABRIC	CATING A SEMI	CONDUCTO	R PRODUC	Γ			
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	Signature		Dated: 6	January 20	03			
KENNETH D. SPRI REG. NO.: 39,843	INGER							
VOLENTINE FRANCOS, PLLC 12200 SUNRISE VALLEY DRIVE, SUITE 150 RESTON, VA 20191 TEL. NO.: (703) 715-0870				I certify that this document and fee is being deposited on with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.				
cc:				Signa	ature of Person	n Mailing Correspondence		

Typed or Printed Name of Person Mailing Correspondence

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AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Hyun-don OH et al.								Docket No.				
Serial No. 09/939,556			ng Date gust 2001	8	Examiner Scott B. GEYER	RTECH	JAN - 7 HNOLOGY (	7 <b>Gzggg</b> Art Unit 2829 CENTER 2800				
Invention: FRUPPMENT FOR FABRICATING A SEMICONDUCTOR PRODUCT												
TO THE ASSISTANT COMMISSIONER FOR PATENTS:  Transmitted herewith is an amendment in the above-identified application.												
	The fee has been calculated and is transmitted as shown below.											
			CLAIMS /	AS AMEND	ED							
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No additional fee is required for amendment.  Please charge Deposit Account No. in the amount of A duplicate copy of this sheet is enclosed.  A check in the amount of to cover the filing fee is enclosed.  The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0238  A duplicate copy of this sheet is enclosed.  Any additional filing fees required under 37 C.F.R. 1.16.  Any patent application processing fees under 37 CFR 1.17.												
KENNETH D. SP REG. NO.: 39,84 VOLENTINE FR 12200 SUNRISE V RESTON, VA 20 TEL. NO.: (703)	43 RANCOS VALLEY 0191	S, PLLC Y DRIVE, SUIT	ΓE 150	Dated:	I certify that on first class ma	t this o	with t er 37 C.F.R. 1	and fee is being deposited the U.S. Postal Service as 1.8 and is addressed to the latents, Washington, D.C.				
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CC:

Typed or Printed Name of Person Mailing Correspondence



SEC.836 RECEIVED

## IN THE UNITED STATES PATENT AND TRADEMARK OFFIGE CHNOLOGY CENTER ?

In re PATENT APPLICATION of:

Hyun-don OH et al.

Group Art Unit: 2829

Serial No.: 09/939,556

Examiner: Scott B. GEYER

Filed: 28 August 2001

**EQUIPMENT FOR FABRICATING** A SEMICONDUCTOR PRODUCT

## **AMENDMENT**

Honorable Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action dated 4 October 2002, the period for response to which is 4 January 2003, please amend the above-identified patent application as follows:

## IN THE CLAIMS:

Please substitute the following claims for the pending claims with the same claim numbers.

1. (Amended) A semiconductor fabricating device, comprising:

an adhesion unit installed in a production line, the adhesion unit having an adhesion chamber that supplies an adhesion enhancing material that reinforces